

Electronic Patent Application Fee Transmittal

Application Number:	10519713			
Filing Date:	30-Dec-2004			
Title of Invention:	Adhesive film for semiconductor, metal sheet with such adhesive film, wiring substrate with adhesive film, semiconductor device, and method for manufacturing semiconductor device			
First Named Inventor/Applicant Name:	Hidekazu Matsuura			
Filer:	William Ivan Solomon/Kelli Harris			
Attorney Docket Number:	1204.44601X00			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1615	3	50	150
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 1 month with \$0 paid	1251	1	120	120
Miscellaneous:				
Total in USD (\$)				270